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# Cool-down acceleration of G-M cryocoolers with thermal oscillations passively damped by helium

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# Outline

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- ❑ Interest in thermal stability and rapid cool-down
- ❑ SHI's helium thermal damper
- ❑ Cool-down with damper and calculations
- ❑ Modified damper gas management and results
- ❑ Additional thermal anchoring

# Superconducting electronic systems

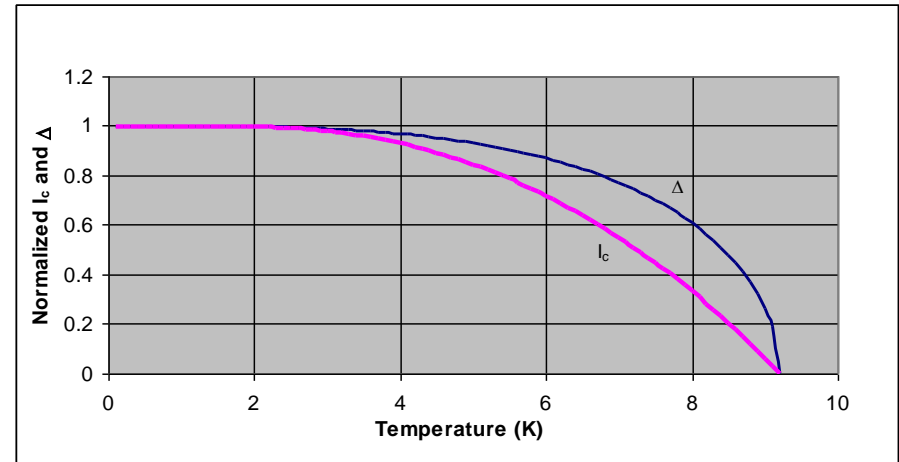


- Hypres and others have developed turn-key S.E. electronic systems:
  - Josephson Junction Primary Voltage Standards
  - Digital RF receivers

# Niobium JJ Ideal Cryo-requirements

## Stable temperature

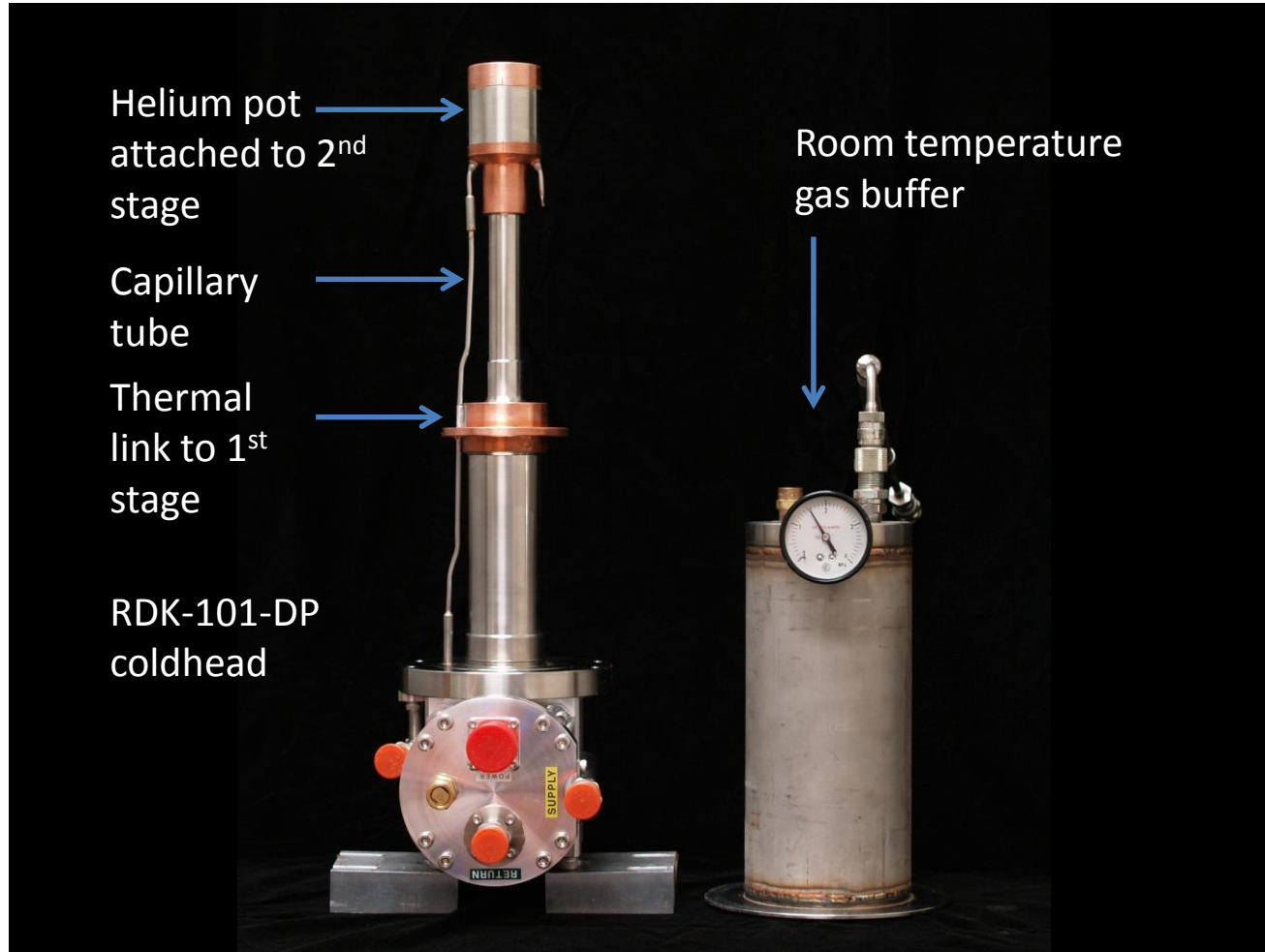
- Critical currents of Junctions and bias points are temperature sensitive



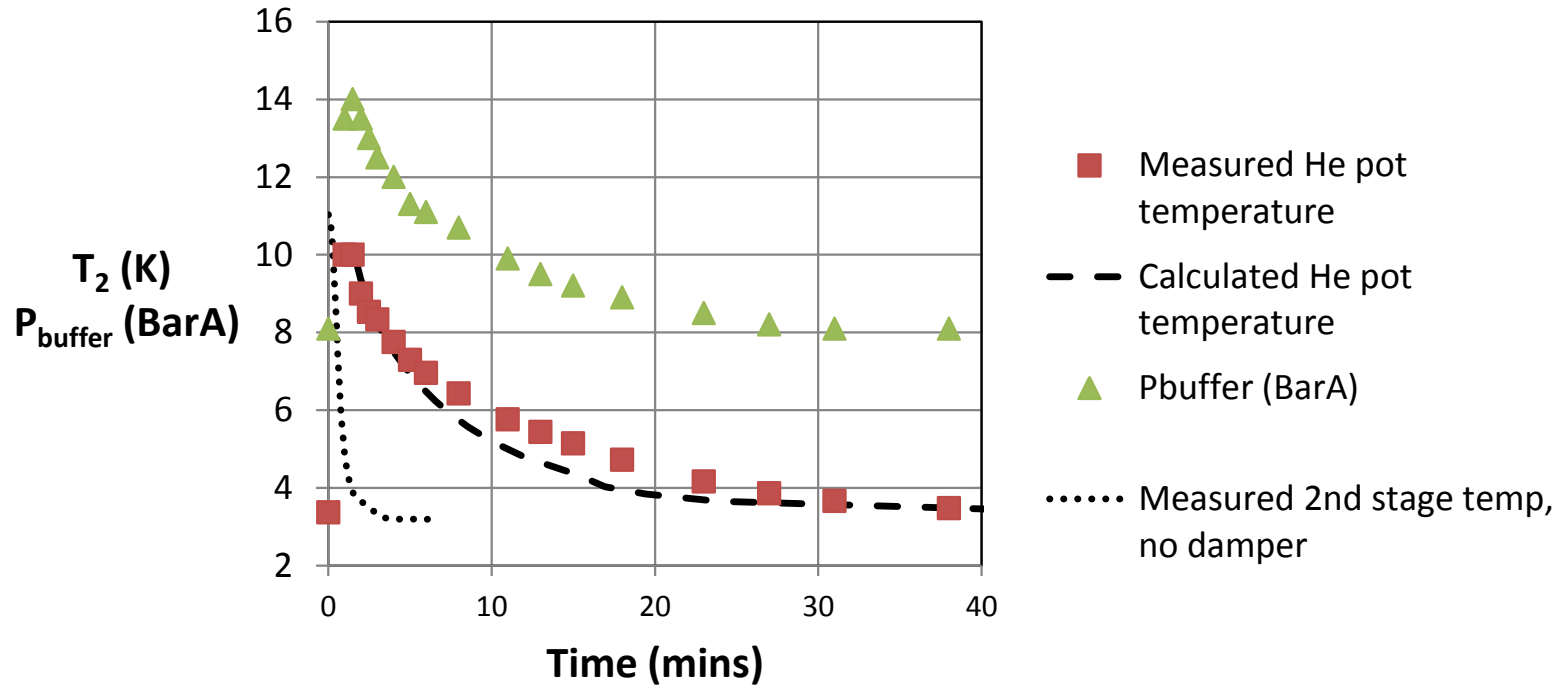
## Fast cool-down

- Quick temperature excursion through superconducting / normal transition
- Extraneous magnetic flux can lower the critical current of random junctions in a circuit, affecting performance – purge by heating to  $T_c$

# SHI RDK-101DP

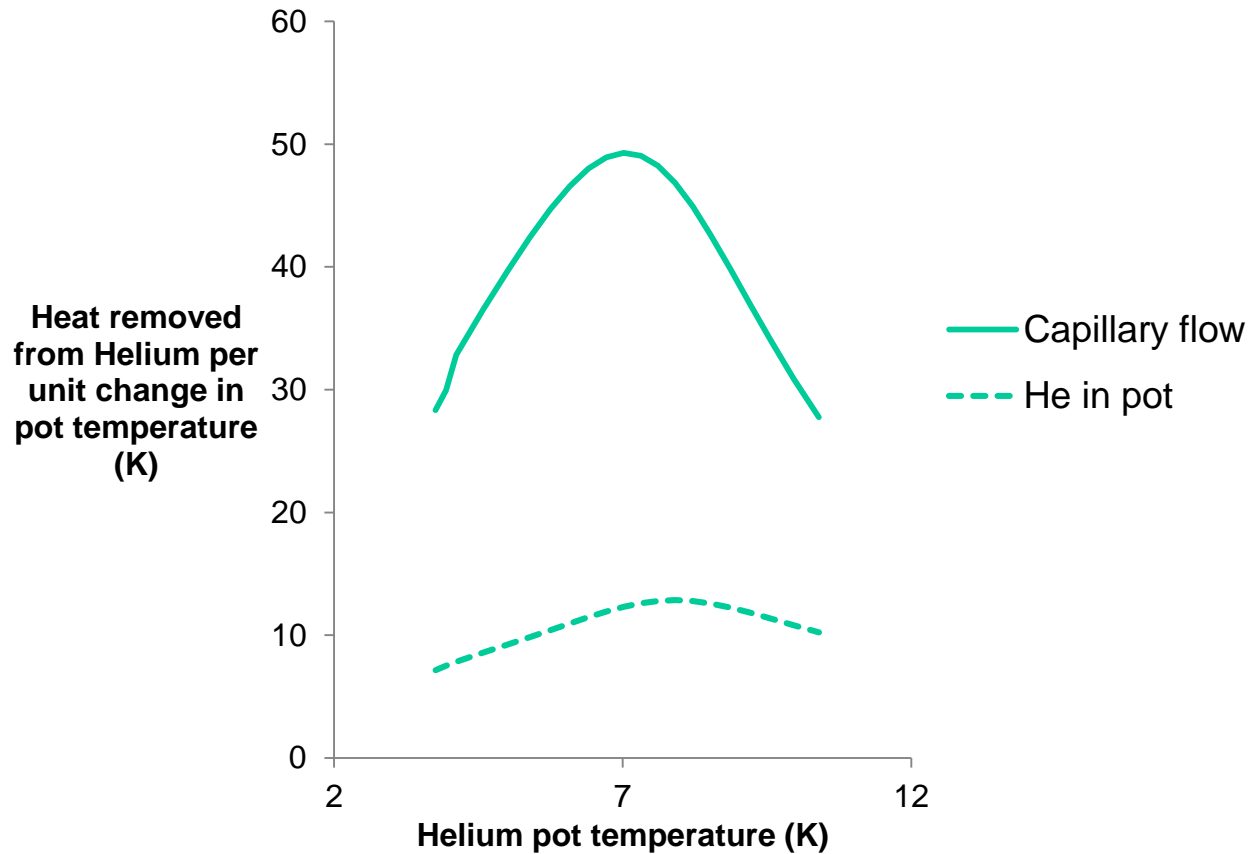


# Damper/No damper Cool-downs



- “Deflux” excursion cool-down much longer with damper
- Buffer pressure follows dropping He pot temperature
- Calculated cool-down agrees reasonably well with measurement

# Dominance of heat from capillary flow



# Calculated cool-down

- Energy balance

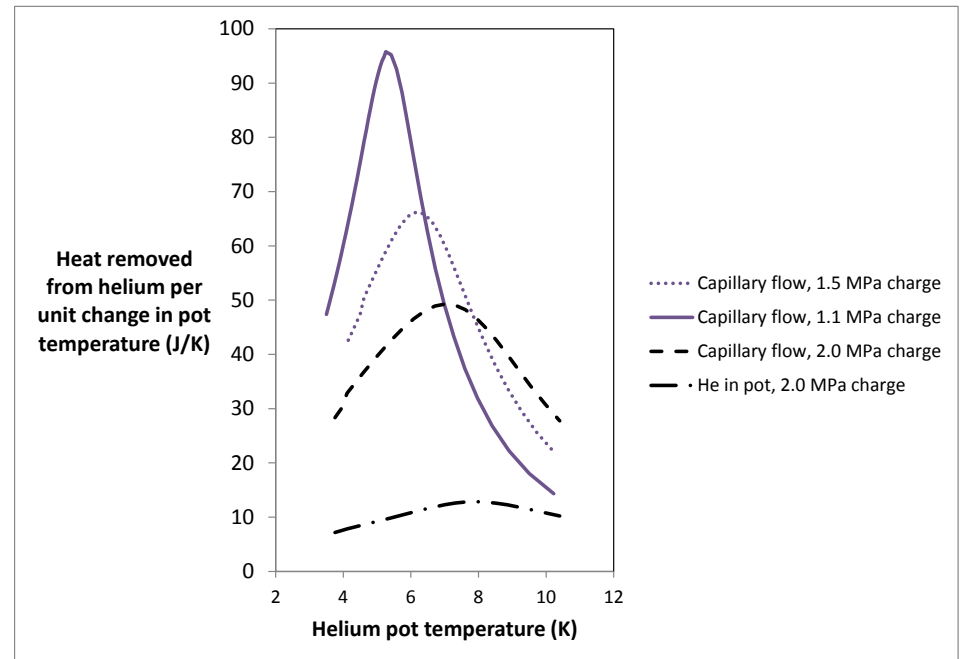
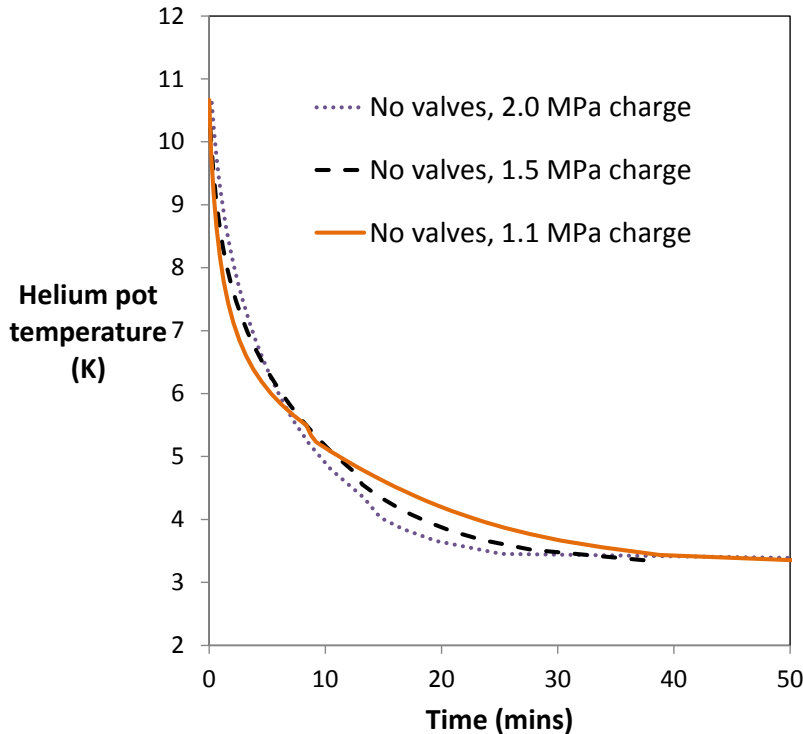
$$\dot{Q}_{ref} = m_p C \dot{T}_p + \Delta h \dot{m}$$

- Mass in He pot known function of pressure, so defining temperature

$$m_p = M - \frac{M_{He} V_b}{RT_{amb}} \{P_p + \Delta P_i\}$$

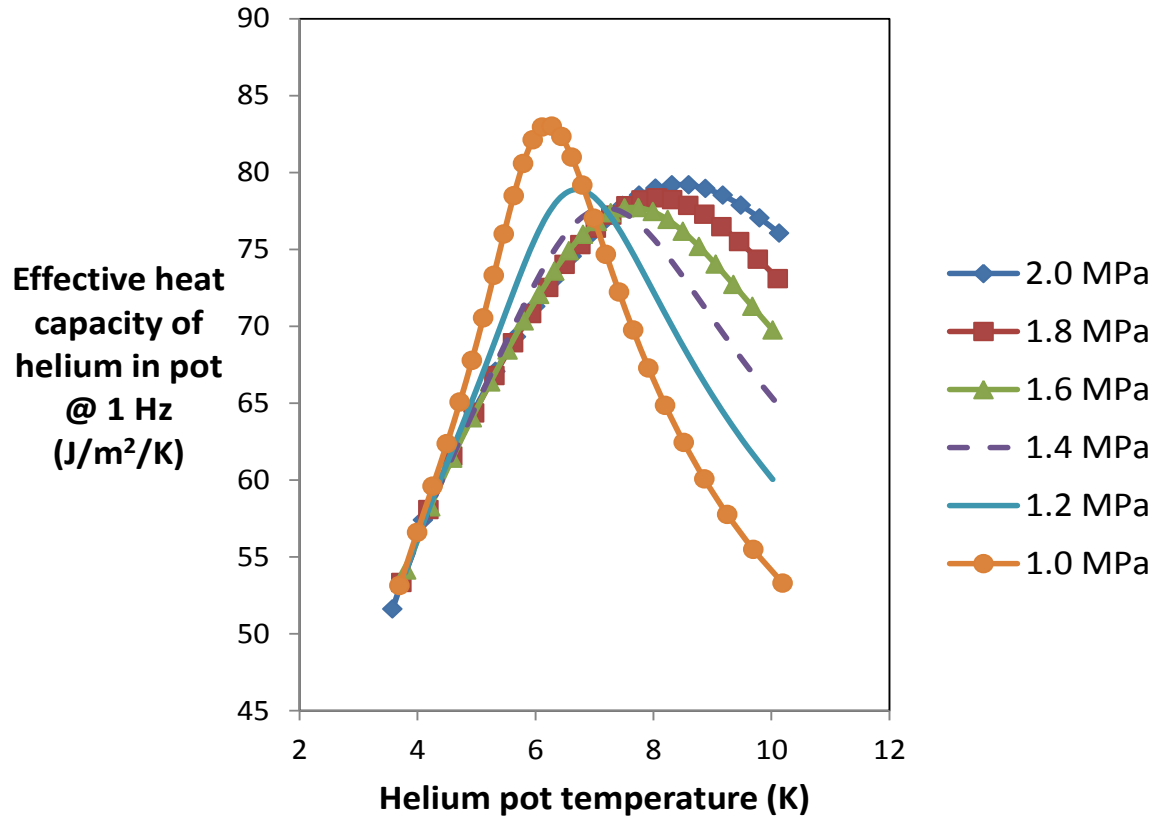


# Low charge pressure cool-downs



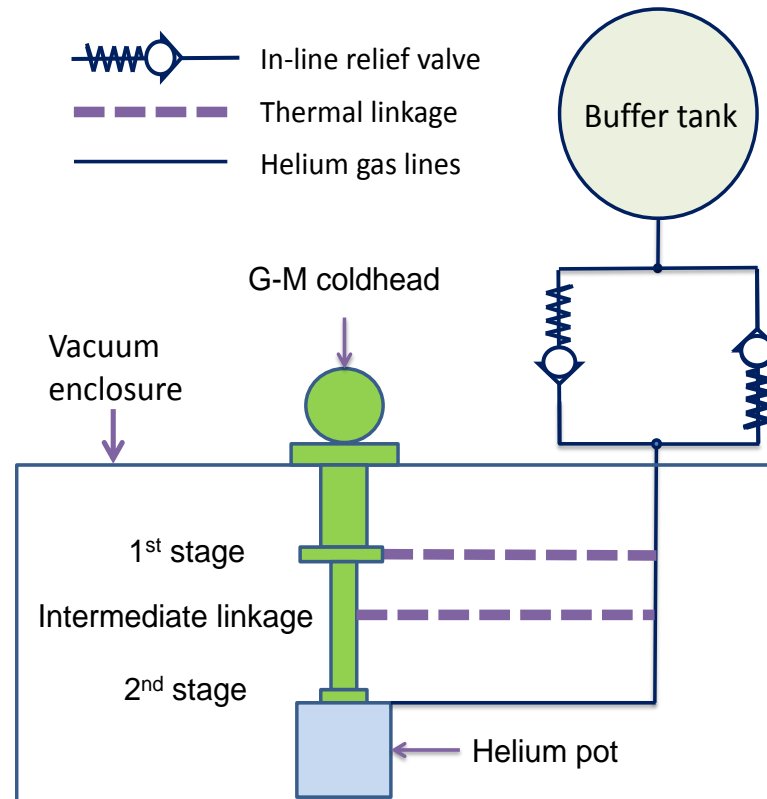
- Lower charge pressure results in *longer* cool-down time
- Total mass flow through capillary is *increased* and peaks at lower temperature
- Rapidly changing density near critical point

# Damping effectiveness vs charge pressure



- Thermal skin depth  $\delta = \sqrt{\frac{\alpha}{\pi f}}$  ~ 0.1mm
- Damping effectiveness/unit area  $\sigma = \delta c_p \rho$

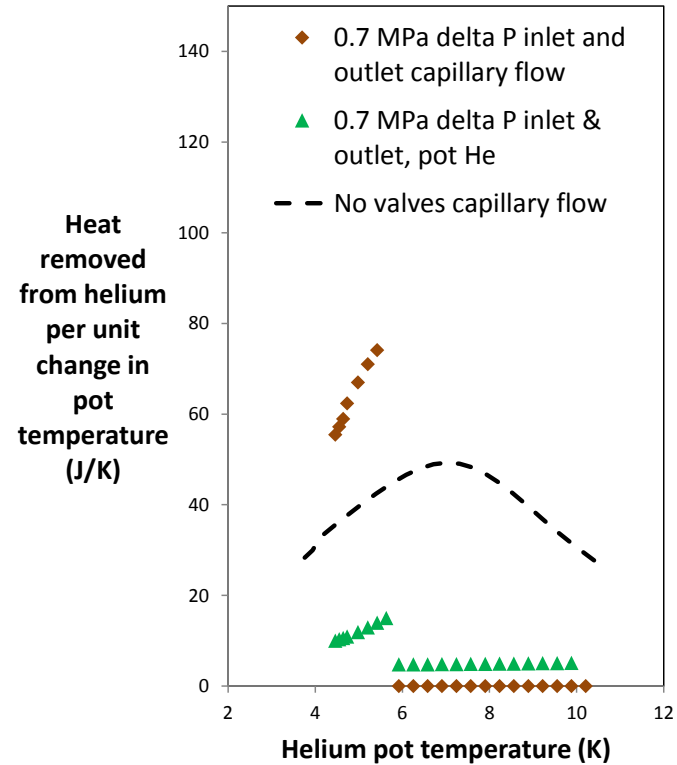
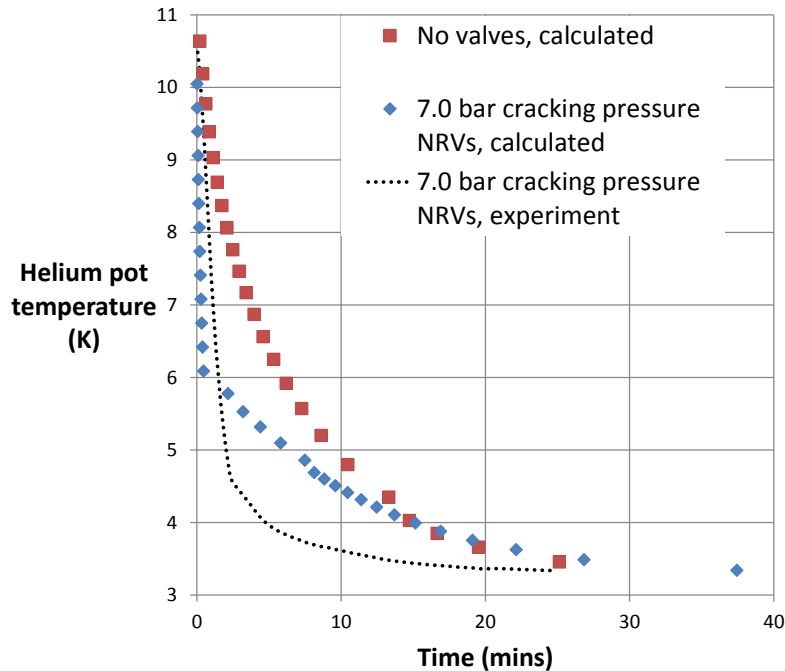
# Modifications to He damper



- **Modifications work passively**

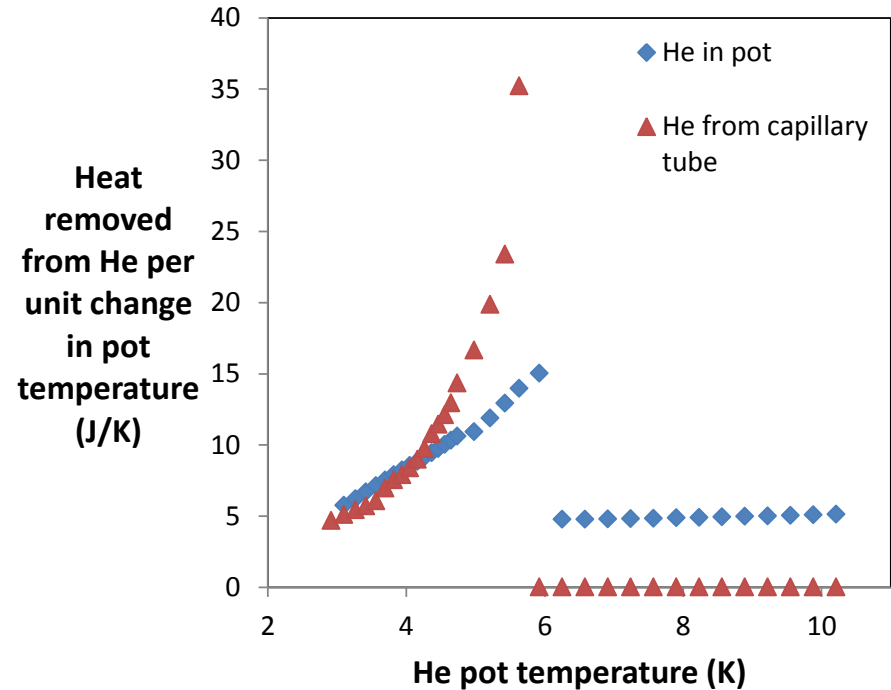
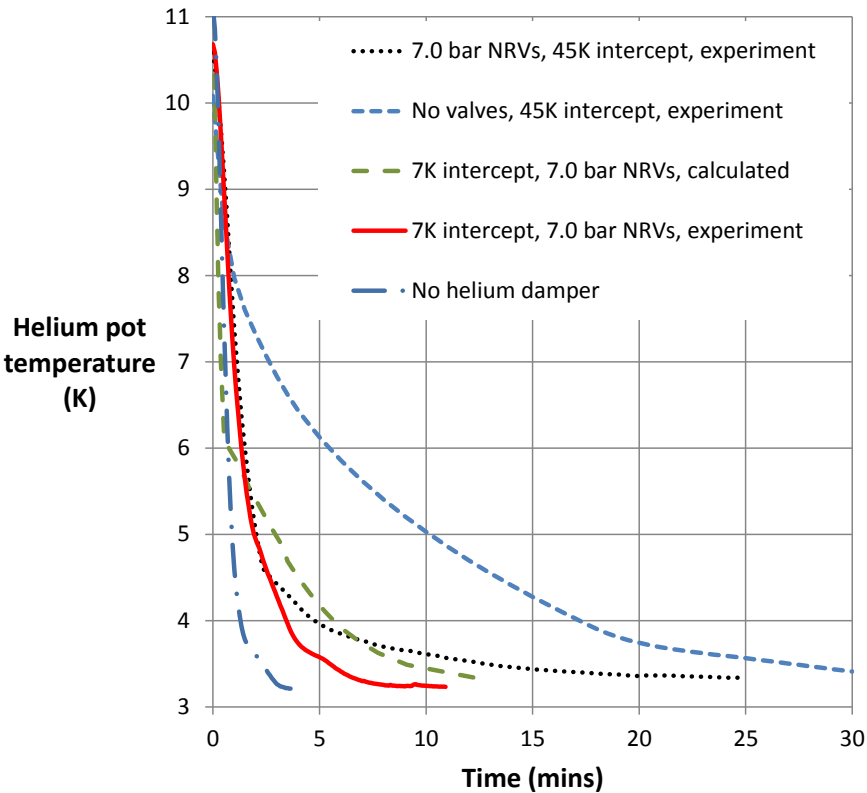
- **Spring-loaded non-return valves set to ~1/3 charge pressure (0.7 bar)**
- **Additional thermal linkage at lower temperature**

# Cool-down with 0.7 MPa c.p. NRVs



- Measured cool-down is dramatically faster than without valves.... WHY??... ..Vapor-lock?.....Thin film of liquid?
- Calculated time to 4 K is no different, in spite of 55% reduction in total capillary flow ---- heat load shifted to lower temperatures

# Addition of 7K thermal intercept to capillary



- Even faster, approaching no-damper time
- Still faster than calculated

# Conclusion

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- **Cool-down from 10K is retarded by warm He injected into He pot**
- **Reduction of charge pressure *increases* cool-down time**
- **In-line relief valves passively restrict buffer-pot mass flow, with dramatic reduction in cool-down time**
- **No reduction in damping**
- **Additional inter-stage thermal intercept reduces time to nearly twice un-damped system**

# Sumitomo SRDK-101D-A11

Parameters	Value
Heat Load (Manufacturer Spec)	0.1 W at 4.2 K and 5 W at 60K
Heat Load (Measured)	0.2 W at 4.2 K and 6 W at 53K
Input Power	1.3 kW, 100±10 V (60 Hz)
Compressor Size	0.45 × 0.385 × 0.40 m <sup>3</sup>
Cold Head Dimension	0.13 × 0.226 × 0.442 m <sup>3</sup>
Compressor Weight	42 kg
Cold Head Weight	7.2 kg



# Temperature Oscillations of Sumitomo Cooler

